



ENVIRONMENTAL AND PACKAGE TESTING DATA FOR PPAK TSC75-6L (POWER IC)					
Stress	Sample Size	Device Hr./Cyc	Condition	Total Fails	Fail Percentage
HAST	55	5,500	130 °C, 85 % RH	0	0.00
Pressure Pot	55	5,280	121°, 15 PSIG	0	0.00
Solder DUNK	110	330	260 °C, 10 SEC	0	0.00
Temp Cycle	55	13,750	- 65 °C - 150 °C	0	0.00